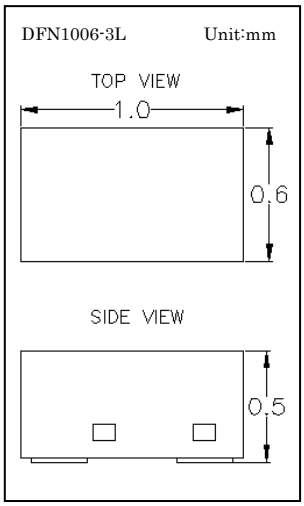
LX3139FB
P-channel MOSFET

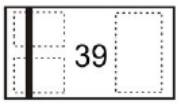
Features

- P-Channel Switch with Low $R_{DS(on)}$
- Surface Mount Package
- ROHS Compliant & Halogen-Free
- ESD Protection

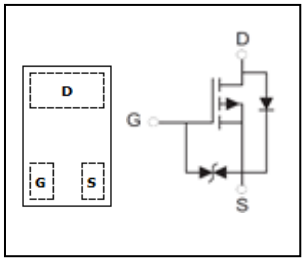
Package



Device Marking Code



Circuit Diagram



Maximum Ratings (Ta=25℃ Unless Otherwise Noted)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	±8	V
I_D	Drain Current-Continuous[*1]	-0.66	A
I_{DM}	Pulsed Drain Current	-2.1	A
P_D	Power Dissipation[*1]	0.15	W
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient[*1]	833	℃/W
Tj	Junction Temperature	150	℃
Tstg	Storage Temperature	-55～+150	℃

Electrical Characteristics @25℃ Unless Otherwise Noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	-20			V
$V_{GS(th)}$	Gate-Threshold Voltage*2	V_{DS}=V_{GS}, I_D=-250μA	0.35	-0.45	-1.1	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-20V, V_{GS}=0V			-1.0	uA
I_{GSS}	Gate-Body Leakage Current	V_{GS} =±8V, V_{DS}=0V			±10	uA
$R_{DS(on)}$	Drain-Source On-Resistance*2	V_{GS}=-4.5V, I_D=-0.55A		530	640	mΩ
		V_{GS}=-2.5V, I_D=-0.45A		730	950	mΩ
		V_{GS}=-1.8V, I_D=-0.35A		1300	1950	mΩ
g_{FS}	Forward Transconductance	V_{DS} =-10V, I_D =-0.54A		1.2		S
V_{SD}	Diode Forward Voltage	I_S=-0.5A, V_{GS}=0V			-1.2	V
Dynamic Characteristics*4						
Ciss	Input Capacitance	V_{DS}=-10V,V_{GS}=0V, f=1MHz		58		pF
Coss	Output Capacitance			5.7		
Crss	Reverse Transfer Capacitance			4.4		
Switching Parameters *4						
td(on)	Turn-on Delay Time*3	V_{GS}=-10V, V_{DD}=-4.5V, I_D=-1.33A,R_{GEN}=3Ω		0.4		nS
Tr	Turn-on Rise Time*3			0.06		
td(off)	Turn-off Delay Time*3			0.02		
Tf	Turn-off Fall Time*3			0.8		

Notes:

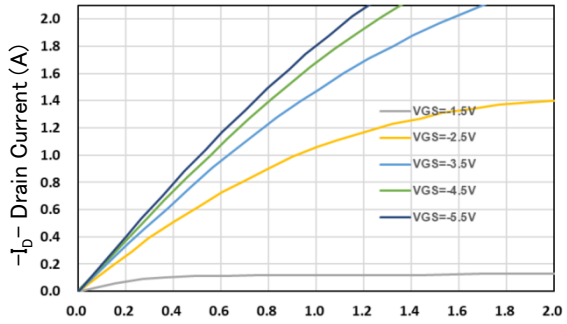
*1. Surface mounted on FR4 board using the minimum recommended pad size.

*2. Pulse Test : Pulse Width=300μs, Duty Cycle=2%.

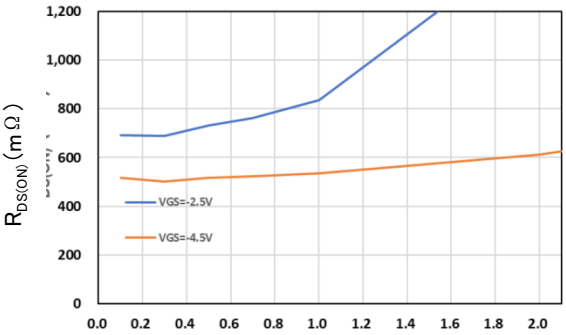
*3. Switching characteristics are independent of operating junction temperatures.

*4. Guaranteed by design, not subject to producting.

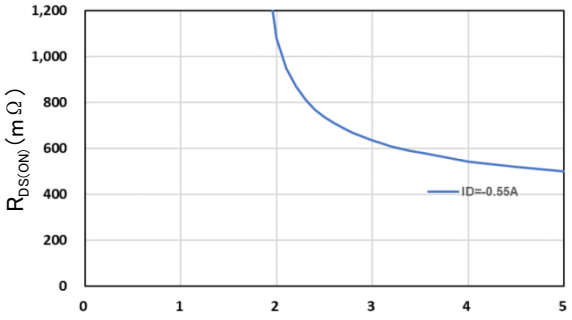
Typical Characteristics



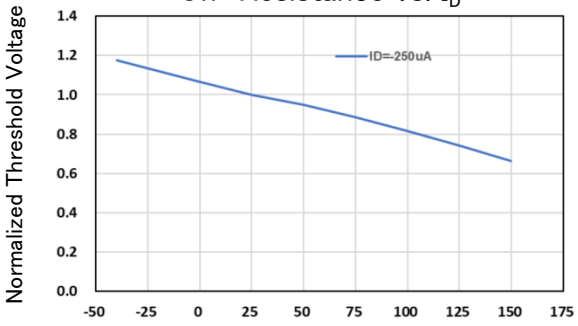
Output Characteristics



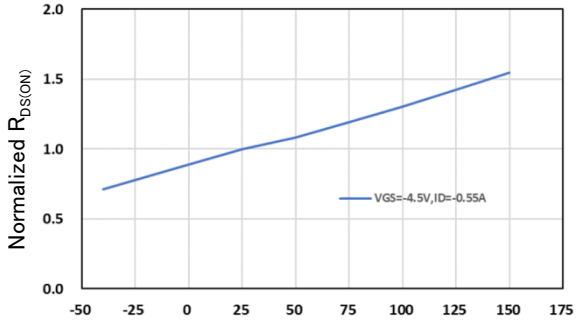
On—Resistance vs. I_D



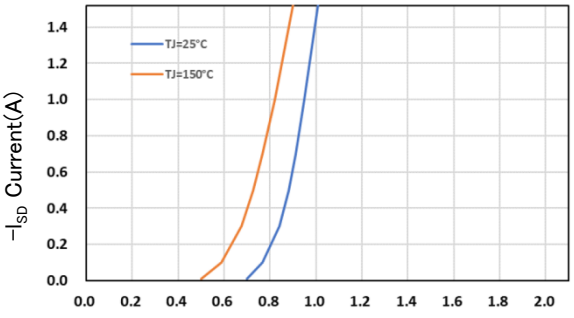
On—Resistance vs. V_{GS}



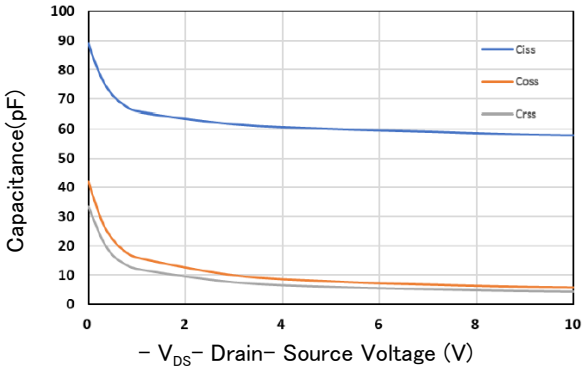
Gate Threshold Voltage



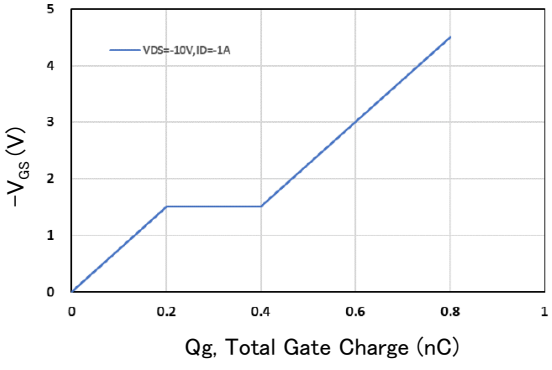
Drain-Source On Resistance



Source-Drain Diode Forward



Capacitance

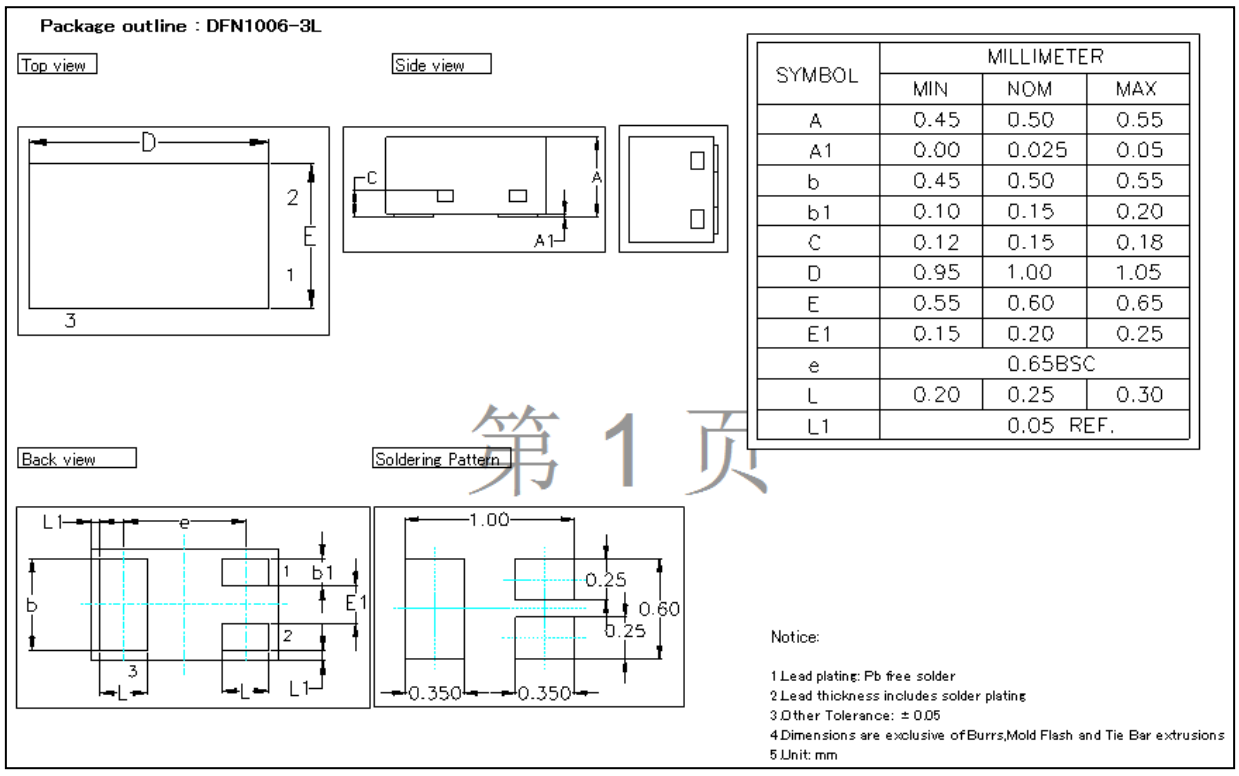


Gate Charge Characteristics

Ordering Information

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
LX3139FB	DFN1006-3L	Tape & Reel 10000pcs /7" Reel	8mm	4mm	Conductive	

Package Dimensions



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	0.025	0.05
b	0.45	0.50	0.55
b1	0.10	0.15	0.20
C	0.12	0.15	0.18
D	0.95	1.00	1.05
E	0.55	0.60	0.65
E1	0.15	0.20	0.25
e		0.65BSC	
L	0.20	0.25	0.30
L1		0.05 REF.	